

Ultrafast recovery Rectifier diode Reverse Voltage50V-1000v Forward current-1A

Features

Glass passivated chip
High surge current capability
Ldeal for surface mounted applications
Low power loss, high efficiency
Plastic Case Material has UL Flammability

Mechanical Data

Package: SMAF

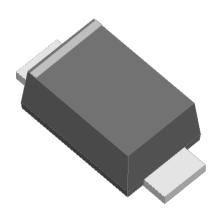
Terminals:Tin Plated leads, solderable per

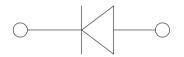
Mil-STD-750 Method 2026

Polarity: As marked

Molding compound meets UL 94 V-0 flammability rating,

ROHS-compliant





Maximum Ratings (Ta=25℃ Unless otherwise specified)

Time Number	CVMDOL	US1							
Type Number	SYMBOL	AF	BF	DF	GF	JF	KF	MF	Umit
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Current	IO _(AV)	1.0				Α			
Peak Forward Surge Current 8.3ms Single half-sine-wave superimposed on rated load(JEDEC Method) on rated	IFSM	25.0							Α
Forward Surge Current (Non-repetitive) @1ms, square wave, 1 cycle, Tj=25°C	6	50.0			Α				
Current squared time @1ms≤t8.3≤ms Tj=25℃, Rating of per diode	l ² t	2.6			A ² S				
Maximum Forward Voltage at 1.0A DC	V_{FM}	1.0 1.3 1.7			V				
Maximum Reverse Current TA = 25 ℃	IR 5.0		uA						
at Rated DC Blocking Voltage TA = 125℃	IIX	100.0			uA				
Maximum reverse recovery time	Trr	50.0 75.0			ns				
Typical Thermal Resistance Between junction and	R_{QJa}	65.0					°C/W		
Operating Junction Temperature Range	T_J	—55to+150			$^{\circ}\!\mathbb{C}$				
Storage Temperature Range	T _{STG}				55to+15	0			$^{\circ}$ C

FIG. 1MAXIMUM AVERAGE FORWARD CURRENT DERATING

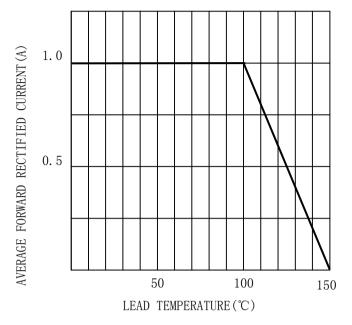


FIG. 2TYPICAL FORWARD CHARACTERISTICS

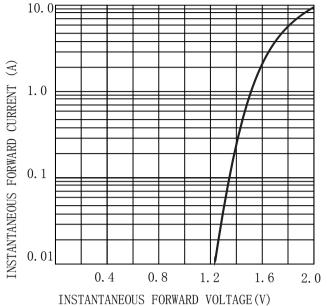


FIG. 3MAXIMUM NON-REPEITIVE SURGE CURRENT

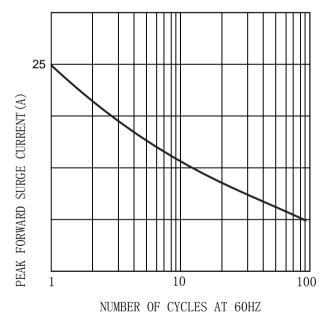
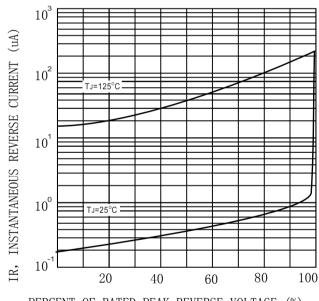


FIG. 4 TYPICAL REVERSE CHARACTERISTICS (per element)



PERCENT OF RATED PEAK REVERSE VOLTAGE (%)

MARKING INFORMATION



= Logo

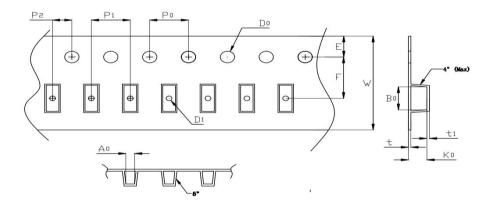
**** = Date Code Marking

US1* = Marking Code

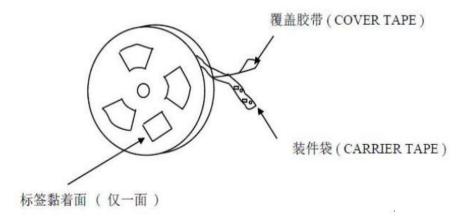
Print according to customer request

PACKING REQUIRMENTS

Carrier tape packing



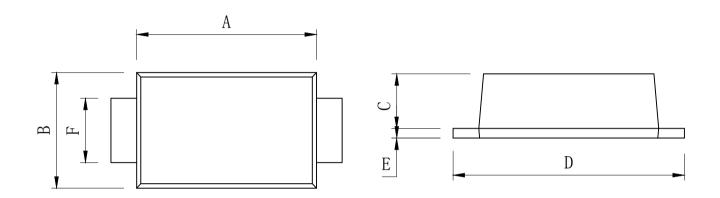
Ī	Specificati ons	Carrier tape type	Ao	Во	Ko	Ро	W	t	Exiplain
Ī	SMAF	Anti-static	2.83± 0.10	4.9± 0.10	1.45± 0.05	4.00± 0.10	12.0± 0.10	0.23± 0.05	



DEVICE TYPE	Tape width		13"Reel		7"Reel		
		Q'TY/REEL (pcs)	BOX/CAR TOON	Q'TY/REEL (pcs)	Q'TY/REEL (pcs)	BOX/CAR TOON	Q'TY/REEL (pcs)
SMAF	12mm	10000	20	200000	3000	64	192000

Outline Dimensions

SMAF



SMAF							
DIM	INC	HES	MM				
	MIN	MAX	MIN	MAX			
A	0. 13	0. 15	3. 2	3.8			
В	0.09	0.11	2.3	2. 7			
С	0.03	0.05	0.8	1.2			
D	0. 16	0.20	4	5			
Е	/	0.01	/	0.3			
F	0.04	0.08	1	2			



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